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(54) **Title:** CIRCUIT FOR A CHIP CARD MODULE

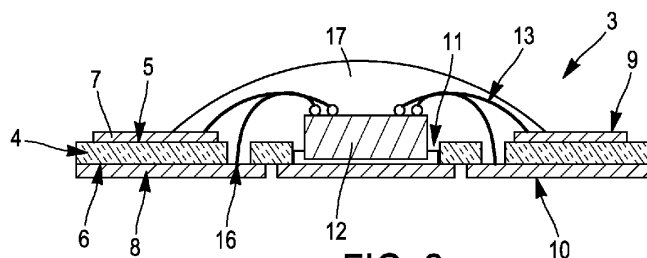


FIG. 2

(57) **Abstract:** A circuit for a chip card module (3) comprising a multilayer structure. This multilayer structure comprises an insulating substrate (4) and a first conductive layer (7) supported by one side of the insulating substrate (4). The first conductive layer (7) is intended to be electrically connected to an electronic chip (12), with electrical wires (13) wire-bonded to the first conductive layer (7). The first conductive layer (7) is a copper-based layer having a Vicker hardness greater than or equal to 100 VHN.

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